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# Supporting Information

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Transformable, Freestanding 3D Mesostructures Based on Transient Materials and Mechanical Interlocking

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Yoonseok Park<sup>†</sup>, Haiwen Luan<sup>†</sup>, Kyeongha Kwon, Shiwei Zhao, Daniel Franklin, Heling Wang, Hangbo Zhao, Wubin Bai, Jong Uk Kim, Wei Lu, Jae-Hwan Kim, Yonggang Huang, Yihui Zhang<sup>\*</sup>, John A. Rogers<sup>\*</sup>

[\*] Prof. John A. Rogers, Corresponding-Author
Department of Materials Science and Engineering, Biomedical Engineering, Neurological Surgery,
Chemistry, Mechanical Engineering, Electrical Engineering and Computer Science Simpson Querrey
Institute and Feinberg Medical School
Center for Bio-Integrated Electronics
Northwestern University Evanston,
Illinois 60208 (USA)
E-mail: jrogers@northwestern.edu

[\*] Prof. Yihui Zhang, Corresponding-Author
Center for Mechanics and Materials, Applied Mechanics Laboratory, Department of Engineering Mechanics,
Tsinghua University,
Beijing 100084, P.R. China
Email: <u>yihuizhang@tsinghua.edu.cn</u>

Dr. Yoonseok Park Center for Bio-Integrated Electronics, Northwestern University, Evanston, IL 60208, USA

Mr. Haiwen Luan Department of Mechanical Engineering, Department of Civil and Environmental Engineering, Department of Materials Science and Engineering, Northwestern University, Evanston, IL 60208, USA.

Dr. Kyeongha Kwon Center for Bio-Integrated Electronics, Northwestern University, Evanston, IL 60208, USA

Mr. Shiwei Zhao Department of Mechanical Engineering, Department of Civil and Environmental Engineering, Department of Materials Science and Engineering, Northwestern University,

Evanston, IL 60208, USA.

Dr. Daniel Franklin Center for Bio-Integrated Electronics, Northwestern University, Evanston, IL 60208, USA

Dr. Heling Wang Department of Mechanical Engineering, Department of Civil and Environmental Engineering, Department of Materials Science and Engineering, Northwestern University, Evanston, IL 60208, USA.

Dr. Hangbo Zhao Center for Bio-Integrated Electronics, Northwestern University, Evanston, IL 60208, USA

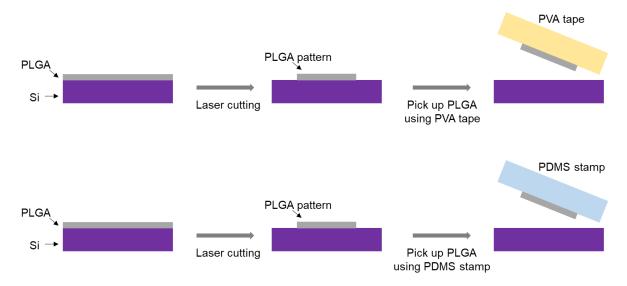
Dr. Wubin Bai Center for Bio-Integrated Electronics, Northwestern University, Evanston, IL 60208, USA

Jong Uk Kim Center for Bio-Integrated Electronics, Northwestern University, Evanston, IL 60208, USA School of Chemical Engineering, Sungkyunkwan University (SKKU), Suwon 16419, Republic of Korea.

Dr. Wei Lu Center for Bio-Integrated Electronics, Northwestern University, Evanston, IL 60208, USA

Jae-Hwan Kim Center for Bio-Integrated Electronics, Northwestern University, Evanston, IL 60208, USA Frederick Seitz Materials Research Laboratory, Department of Materials Science and Engineering, University of Illinois at Urbana–Champaign, Urbana, Illinois 61801, USA.

Prof. Yonggang Huang Center for Bio-Integrated Electronics, Department of Mechanical Engineering, Department of Civil and Environmental Engineering, Department of Materials Science and Engineering, Northwestern University, Evanston, IL 60208, USA.



**Figure S1**. Schematic illustration of steps for preparation of patterned PLGA and transfer to PVA tape and a PDMS stamp.



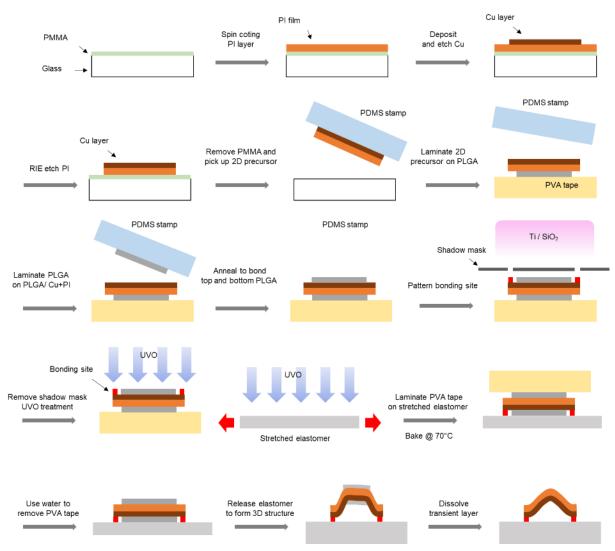
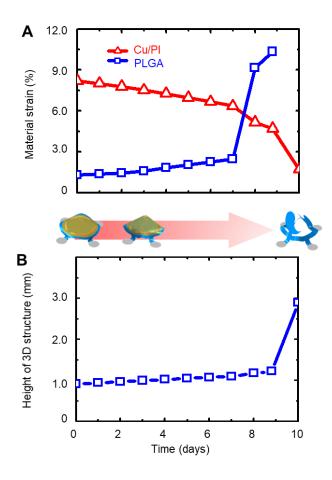


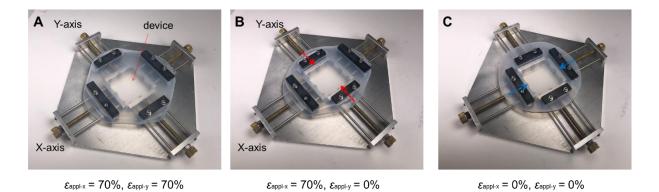
Figure S2. Schematic illustration of steps for fabricating 3D transformable mesostructures.



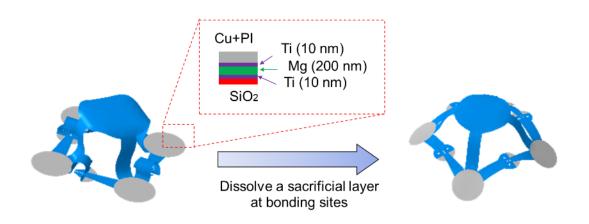
**Figure S3**. Quantative data of transforming 3D mesostructures. (A) Material strain of Cu/PI and PLGA layer and (B) height of transformable 3D structures over 10 days with images of FEA predictions.

3D	Intermediate	Transformed
FEA		
Experimental	R	<u> </u>

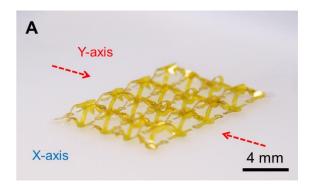
**Figure S4**. Experimental images and FEA predictions of an unusual 3D shape that forms upon dissolution of a transient layer of PLGA. The two non-transient parts lean against one another to hold an 3D structure uniquely realizable in this system. Scale bar, 1 mm.

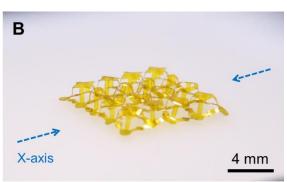


**Figure S5:** Optical images of a customized equal-biaxial stretching stage with an elastomer. (A) initial state (70% stretching X and Y-axis), (B) Releasing the strain along the Y-axis to 0% to interlock the hooks and lugs on the Y axis, (C) Releasing the strain along the X axis to complete the interlocking system.

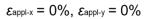


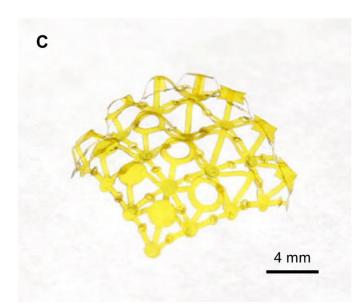
**Figure S6**. Schematic illustration of releasing 3D mesostructure by dissolving a sacrificial layer at the bonding sites in water. Bonding sites include 200 nm layers of Mg that can be dissolved in water.



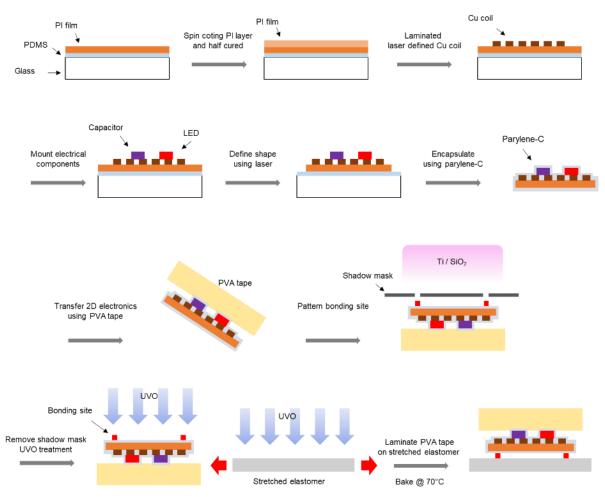


 $\varepsilon_{appl-x} = 70\%$ ,  $\varepsilon_{appl-y} = 0\%$ 





**Figure S7:** Optical images of a 4 by 4 array of freestanding 3D stuctures based on mechanical interlocking. (A) Interlocking of hooks and lugs along the Y-axis (B) and X-axis. A freestanding 3D structure consists of a 4 by 4 array of interlocking features.



**Figure S8**. Schematic illustration of steps for fabricating 4D electronics, transformable and freestanding.

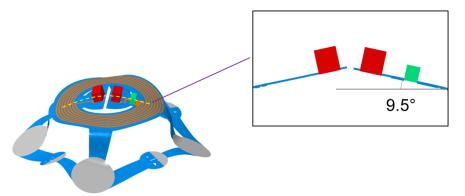


Immerged in PBS Day 0 @ 70°C

Immerged in PBS Day 3 @ 70°C

Fully dissolved Day 10 @ 70°C

**Figure S9**. Photograph images of 3D electronics at various states of immersion in phosphate-buffered saline (PBS) at 70°C. Scale bar 3 mm.



**Figure S10**. Schematic illustration of angular change of light emitting 3D electronics by dissolution of a transient layer.



**Figure S11**. Captured images during transformation of 3D device from a video (transform.mp4). For accelerating dissolution of PLGA, we immersed 4D structure into a solution (Aceton:DI, 1:1) instead of PBS.

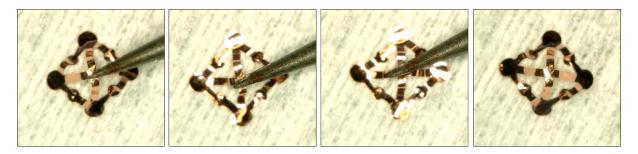


Figure S12: Captured images of a device (mechanical stablility test) from a video (robust.mp4).